



**ON Semiconductor®**

# **Motor Drive Modules Support Rapid Design Cycles and Enhanced Efficiency and Reliability**

# Motor Drive Modules Support Rapid Design Cycles and Enhanced Efficiency and Reliability

The growth of motion control applications, coupled with environmental, commercial and legislative pressure to reduce energy consumption, means that efficiency is at the top of the design agenda for motor-based systems.

The International Energy Agency estimates that electric motors account for almost half (46%) of total global energy consumption, thus making them a focus for energy efficiency initiatives. Energy efficiency is sufficiently important that, in 2009, the European Union issued an energy-related products directive (ErP) 2009/125/EC. While the directive focused on multiple energy-consuming devices, EU regulation 640/2009 specifically relates to electric motors, whether they are sold as stand-alone devices or as part of larger equipment.

Making the situation more complex is the fact that there is an extremely wide range of electric motor applications covering multiple sectors, all of which require reliable, energy-efficient solutions.

In the home, motors are found in white goods such as refrigerators, kitchen appliances, washers and dryers. Cooling devices such as air conditioners and fans are also popular applications.

Industrial and commercial applications such as those found in factories and large offices also use motors for cooling and heating (HVAC). However, there are many more applications to be found including pumps and fans, air and liquid compression, large computers, escalators, elevators, conveyors, hoists, cranes, tools, industrial-grade laundry, cleaning and cooking equipment.

Electric vehicles use high voltage electric motors not only for traction but also for air-conditioning compressors, coolant circulation pumps and transmission oil pumps in hybrid electric vehicles.

Engineers can choose from many types of electric motors based on factors such as efficiency, power, size, reliability, ease of control, and cost. The most commonly used motors include AC induction motors (ACIM), brushed DC motors, stepper motors, brushless DC motors (BLDC) and permanent magnet synchronous motors (PMSM).

## Critical Choices for Designers

Critical design factors and challenges for motor control architectures are efficiency, reliability, noise reduction,

thermal performance, available board space, and ease of design. Once the optimum motor has been chosen, it becomes important to carefully select the approach for driving the system.

Many designers prefer using fully integrated, off-the-shelf solutions that reduce design time and risk. Leading semiconductor manufacturers are addressing this requirement by combining expertise in power semiconductor technology, advanced packaging techniques, and application knowledge to create dedicated, integrated solutions for motor control and industrial inverter applications. Integrating motor drive and protection circuitry into a single package, for example, creates a module that can significantly simplify and accelerate system design. These modules are 'pre-optimized' with important issues such as EMI already addressed. And by integrating all of the semiconductor devices into a single package, thermal issues are reduced and less PCB space is required.

Additional commercial advantages arise from the fact that, once the design enters the manufacturing phase, the lowered component count reduces assembly and inventory management costs.

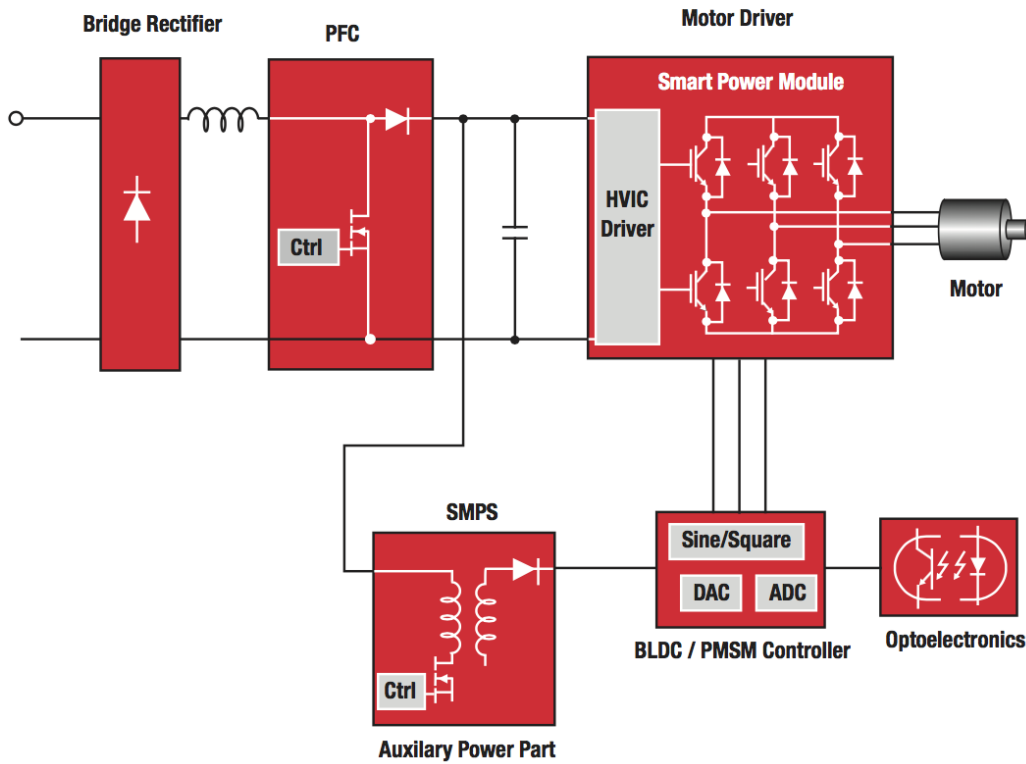
When selecting a supplier, designers need to pay attention to the specific solution for the existing design but should also keep in mind other factors; for example, does the supplier offer a broad range of solutions that allow the design to be scaled up and down to meet future application requirements.

## A Broad Range of Modular Motor Control Solutions

Figure 1 illustrates the elements of a high voltage motor control system. ON Semiconductor's broad product portfolio includes all of the key elements required for the key functional blocks:

- Motion Power Module – integrated solutions that support designs from low-power (20 W) to high-power (10 kW)
- BLDC Controller (Brushless DC/Permanent Magnet Synchronous Motor) – mixed-signal ICs exclusively for motor control that eliminate the need for complex and expensive DSPs (Digital Signal Processors)
- PFC (Power Factor Correction) – PFC modules that minimize input current distortion, reduce power loss, and save energy and cost
- Optocouplers – provide isolation from high-voltage devices in motor control designs
- SMPS (Switched Mode Power Supply) – power management devices used in Flyback converter designs

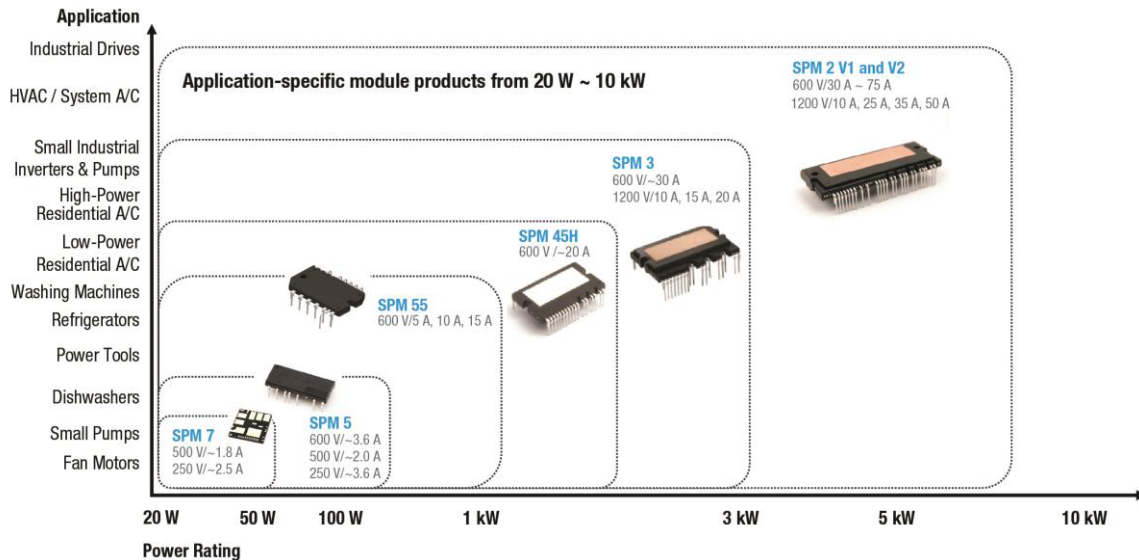
## Motor Control System



**Figure 1. Motor Control Systems Contain Multiple Functional Blocks**

The motion power modules provide a fully-featured, high-performance three-phase inverter output stage and

optimized gate drive technology to minimize EMI and losses, and provide multiple on-module protection features.



**Figure 2. Board Power Module Range Covers Multiple Applications up to 10 kW**

While the power module range offers key benefits such as UL certification (UL1557), improved thermal performance due to direct-bond copper (DBC), and better reliability with

higher noise / surge immunity across the range, each device is optimized to suit a specific application set.

### SPM 2 Series

Typically used in HVAC, industrial inverters, servomotors, pumps or fan motors, the 600 V and 1200 V SPM 2 module series addresses three-phase inverter based motor drive applications up to 10 kW. Reliability is

reinforced by using low-loss NPT and field-stop trench IGBTs with DBC package technologies that achieve greater than 10% reduction in module losses, with longer short-circuit rating capabilities and embedded protection circuits.

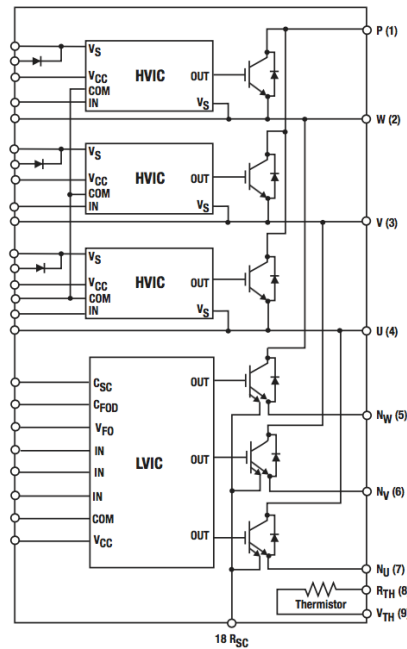


Figure 3. SPM 2 Block Diagram

### SPM 3 Series

Supporting a broad range of applications including HVAC, commercial air conditioners, compact industrial level inverters, servo-drivers, fan motors and pumps, the 500 V, 600 V, and 1200 V SPM 3 module series covers a wide range of power applications up to 3 kW. This solution

is compatible with AC induction, BLDC, and PMSM motor types. Separate open emitter terminals are available for each phase to support the widest variety of control algorithms. SPM 3 modules are offered in very low thermal resistance packaging AL2O3 DBC, ceramic substrate, and FullPAK options.

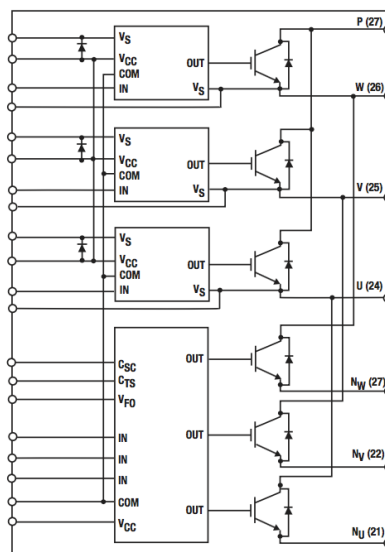


Figure 4. SPM 3 Block Diagram

### SPM 45 Series

Aimed primarily at residential applications including appliance inverters (such as residential A/C), washing machines, refrigerators, pumps, industrial fans and compact inverters, the 600 V SPM 45 module series provides compact and high-performance inverter solutions for AC motor drives in lower power applications up to  $\pm 2$  kW. The series targets cost-sensitive applications below 30 A,

offering ceramic substrate packaging with built-in bootstrap diodes. System reliability is further enhanced by a built-in NTC for temperature monitoring, integrated under-voltage lock-out (UVLO) function and over-current protection input.

Three separate open-emitter pins for low-side IGBTs enable three-leg current sensing. Built-in bootstrap diodes and dedicated  $V_S$  pins simplify PCB layout.

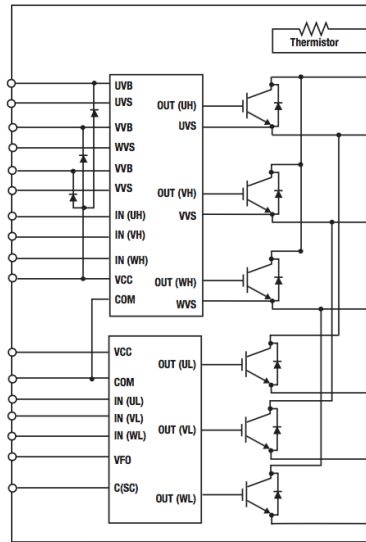


Figure 5. SPM 45 Block Diagram

### SPM 55 Series

Also intended for residential use – including appliance inverters (such as residential A/C), washing machines and refrigerators – the 600 V SPM 55 modules provide a fully-featured, high-performance inverter output stage for lower power AC Induction, BLDC, and PMSM motors up to 1 kW. The built-in, high-speed HVIC requires only

a single supply voltage and translates the incoming logic-level gate inputs to the high-voltage, high-current drive signals required to properly drive the modules' robust short-circuit-rated IGBTs. Separate negative IGBT terminals are available for each phase to support the widest variety of control algorithms.

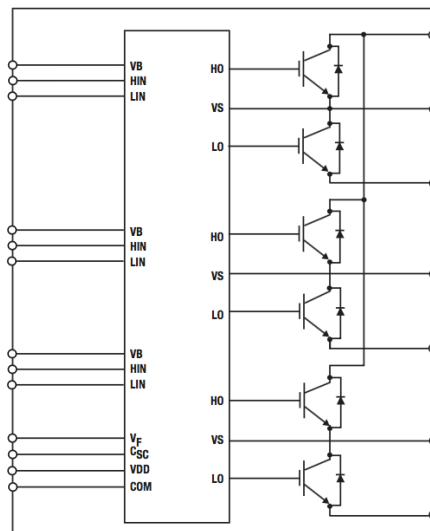


Figure 6. SPM 55 Block Diagram

### SPM 5 Series

Serving a broad application set including dishwashers, ceiling fans, pumps and fans for lower power air conditioners, the 250 V, 500 V, and 600 V SPM 5 module series provides optimized gate drive to minimize EMI and

losses for three-phase motor drive applications below 200 W. Modules are offered in package options of DIP, double DIP and SMD. Separate open-source MOSFET terminals for each phase support the widest variety of control algorithms.

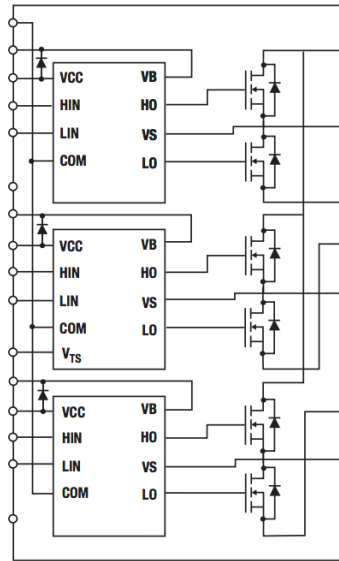


Figure 7. SPM 5 Block Diagram

### SPM 7 Series

Intended for lower power applications such as small pumps, pedestal and ceiling fans below 100 W, the advanced SPM 7 (250 V, 500 V, 600 V) modules provide a fully-featured, high-performance three-phase inverter output stage for AC induction, BLDC and PMSM motors. These modules integrate the optimized gate drive of the built-in MOSFETs to minimize EMI and losses, while also

providing multiple protection features. The built-in HVIC translates incoming logic-level gate inputs to the high-voltage, high-current drive signals required to properly drive the internal MOSFETs. Separate open-source MOSFET terminals are available for each phase to support the widest variety of control algorithms. The PQFN package can deliver board space savings of up to 50%, while minimizing EMI and losses.

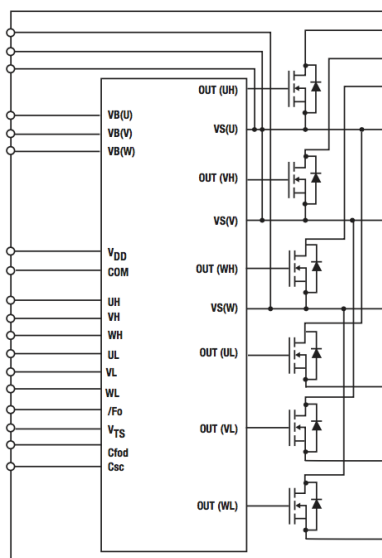


Figure 8. SPM 7 Block Diagram

## Packaging Considerations

The complete SPM range comprises multiple packaging options including dual-in-line package (DIP) and surface-mount (SMD). Each of these is optimized to

minimize PCB area, yet provide a simple method for adding additional cooling for high-power applications. The devices offer a far simpler mechanical and thermal arrangement than a discrete solution that would contain multiple ‘hot spots’.



**Figure 9. The SPM Range Offers a Wide Variety of Packaging, Including SMD**

By following a few simple guidelines, designers can easily create a thermally efficient solution that meets the required safety spacing guidelines. This can be illustrated with a more detailed examination of the SPM 2 package.

Creepage and clearance distances ensure safety and compliance with all relevant safety standards. The package itself defines the distances for the power and control terminals (as shown in the table below); the designer needs to ensure that the PCB layout maintains these distances.

Location	Clearance [mm]	Creepage Distance [mm]
Between Power Terminals	7.80	8.00
Between Control Terminals	3.05	6.85
Between Terminals & H/S	3.8	6.06

**Figure 10. Recommended Spacings for SPM 2 Module**


When mounting a module to a heatsink, adhering to simple procedures will ensure success. The heatsink should

have a flatness not exceeding  $-50/+100 \mu\text{m}$ , and a  $150 \mu\text{m}$  layer of thermally conductive grease should be applied evenly across the contact surface, ensuring there is no dust or debris present.

Excessive and / or uneven fastening force must be avoided as this could apply stress to the silicon, thereby damaging the device. The correct procedure involves using M4 SEMS screws with a plain and spring washer and pre-tightening both screws to approximately 25% of the final torque, before final tightening with a torque-controlled screwdriver.

## Summary

Motor control can be challenging for the less-experienced designers, not least due to stringent efficiency and reliability targets as well as standards-driven safety requirements. A modular approach is an obvious choice for newcomers to motor control, yet many experienced designers also value the multitude of benefits that modules offer. These include a pre-optimized design, reduced size, reduced BOM cost and component count, and assurance that reliability, safety, and efficiency targets will be met.

ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## PUBLICATION ORDERING INFORMATION

### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor  
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA  
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
Email: [orderlit@onsemi.com](mailto:orderlit@onsemi.com)

**N. American Technical Support:** 800-282-9855 Toll Free  
USA/Canada  
**Europe, Middle East and Africa Technical Support:**  
Phone: 421 33 790 2910

**ON Semiconductor Website:** [www.onsemi.com](http://www.onsemi.com)

**Order Literature:** <http://www.onsemi.com/orderlit>

For additional information, please contact your local Sales Representative